

Ultramid® 8200 HS

Polyamide 6



Product Description

Ultramid 8200 HS is a heat stabilized, medium viscosity, PA6 injection molding homopolymer, exhibiting resistance to sink-mark formation in thick sections, and improved toughness over conventional lower viscosity grades. It possesses a combination of strength, stiffness and toughness properties as well as excellent heat, chemical and abrasion resistance. It is available in natural and pigmented versions.

Applications

Ultramid 8200 HS is generally recommended for application such as wiring devices, plugs, receptacles, gears, connectors, convoluted tubing, filter housings, hinges, and textile components.

PHYSICAL	ISO Test Method	Property Value	
Density, g/cm ³	1183	1.13	
Moisture, %	62		
(24 Hour)		1.6	
(50% RH)		2.7	
(Saturation)		9.5	
MECHANICAL	ISO Test Method	Dry	Conditioned
Tensile Modulus, MPa	527		
23C		2,700	
Tensile stress at yield, MPa	527		
-40C		136	120
23C		80	39
121C		23	-
Tensile strain at yield, %	527		
23C		5	16
Nominal strain at break, %	527		
23C		25	>50
Flexural Strength, MPa	178		
23C		82	-
Flexural Modulus, MPa	178		
23C		2,400	-
IMPACT	ISO Test Method	Dry	Conditioned
Charpy Notched, kJ/m ²	179		
23C		3.5	-
Charpy Unnotched, kJ/m ²	179		
23C		N	-
THERMAL	ISO Test Method	Dry	Conditioned
Melting Point, C	3146	220	-
HDT A, C	75	60	-

Processing Guidelines

Material Handling

Max. Water content: 0.15%



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Product is supplied in sealed containers and drying prior to molding is not required. If drying becomes necessary, a dehumidifying or desiccant dryer operating at 80 degC (176 degF) is recommended. Drying time is dependent on moisture level, but 2-4 hours is generally sufficient. Further information concerning safe handling procedures can be obtained from the Material Safety Data Sheet. Alternatively, please contact your BASF representative.

Typical Profile

Melt Temperature 240-285 degC (464-545 degF)
Mold Temperature 65-80 degC (149-176 degF)
Injection and Packing Pressure 35-125 bar (500-1500 psi)

Mold Temperatures

A mold temperature of 65-80 degC (149-176 degF) is recommended, but temperatures of as low as 10 degC (50 degF) can be used where applicable.

Pressures

Injection pressure controls the filling of the part and should be applied for 90% of ram travel. Packing pressure affects the final part and can be used effectively in controlling sink marks and shrinkage. It should be applied and maintained until the gate area is completely frozen off.

Fill Rate

Fast fill rates are recommended to ensure uniform melt delivery to the cavity and prevent premature freezing.

Note

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